



BOARD LEVEL COOLING – 2327B

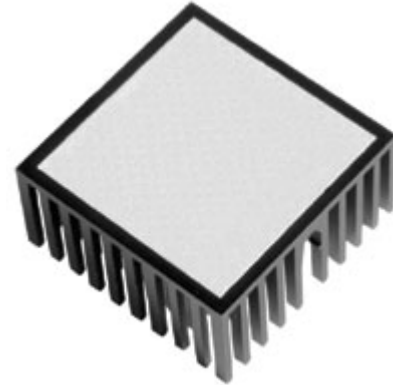
2327B is a square pin fin board level heat sink designed to cool BGA and FPGA devices. This heat sink uses pressure sensitive adhesive for mounting. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
2327B-TACHG	BGA, FPGA

HEAT SINK DETAILS

Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Tape
Thermal Interface Material	T405R Chomerics Tape for Metal Surfaces



Property	Details
Heat Sink Width (mm)	27.94
Heat Sink Length (mm)	28.07
Heat Sink Height (mm)	15.24
Heat Sink Mounting Direction	Horizontal, Vertical

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

